

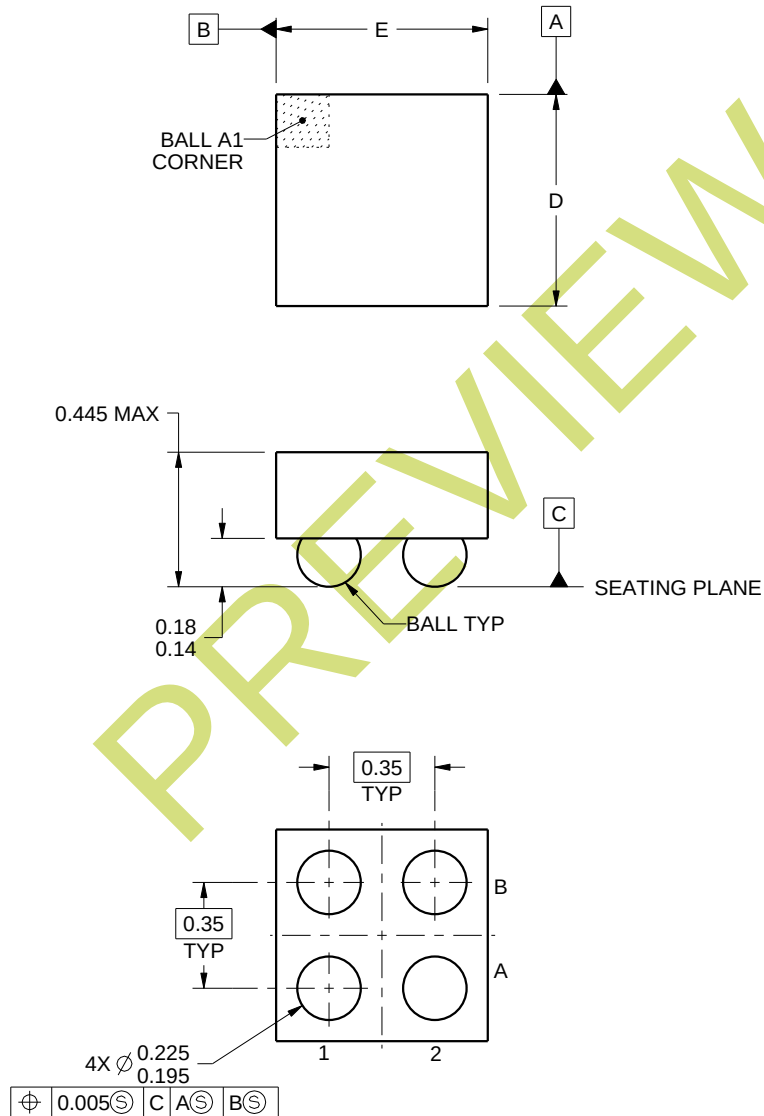


PACKAGE OUTLINE

YKE0004

DSBGA - 0.445mm max height

DIE SIZE BALL GRID ARRAY



4220102/A 07/2013

NOTES:

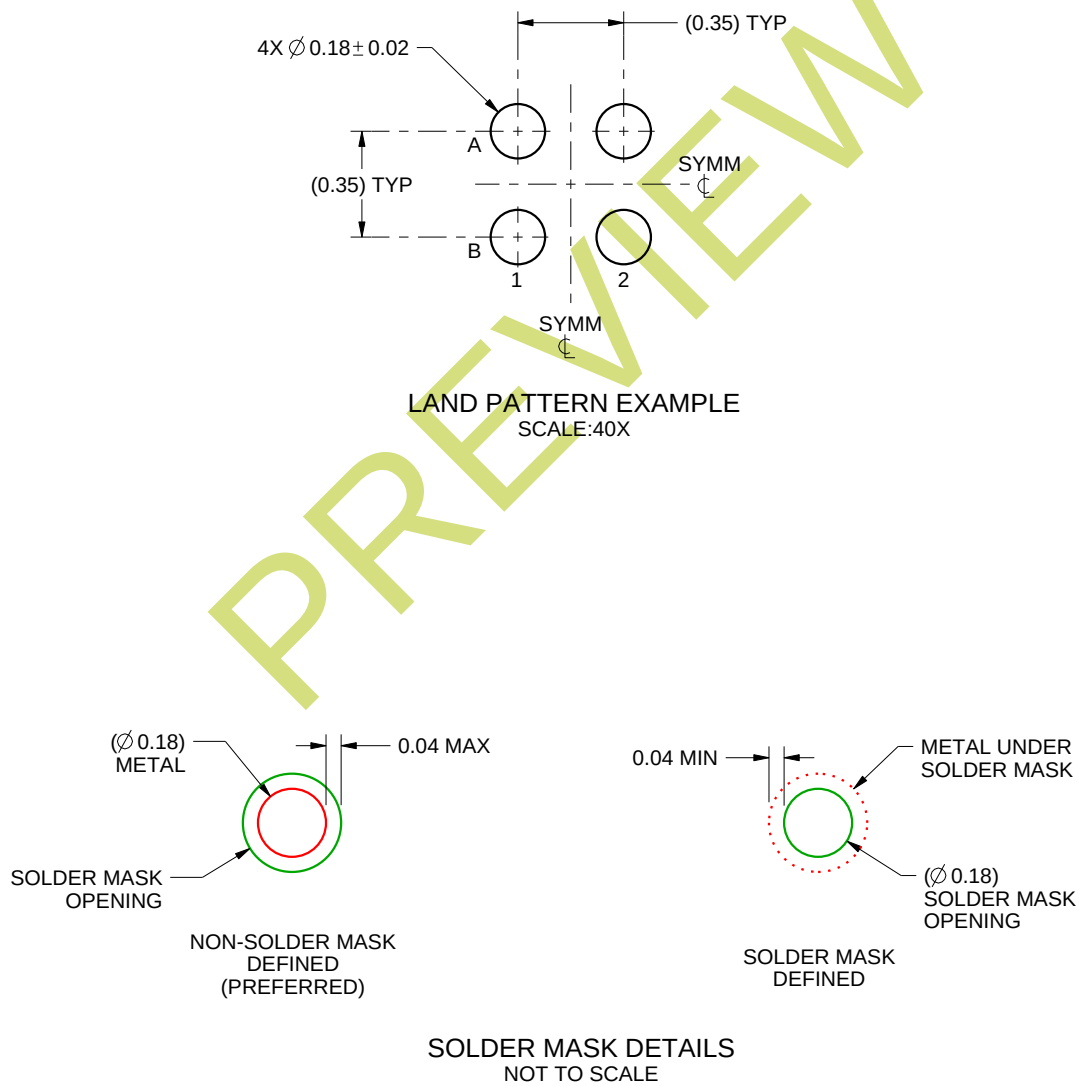
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

YKE0004

DSBGA - 0.445mm max height

DIE SIZE BALL GRID ARRAY



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NOTES: (continued)

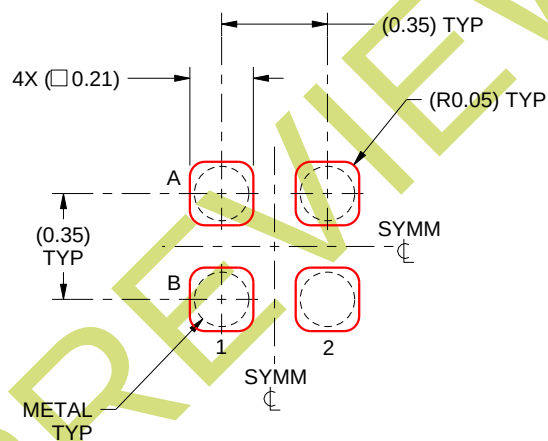
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. Refer to Texas Instruments Literature No. SBVA017 (www.ti.com/lit/sbva017).

EXAMPLE STENCIL DESIGN

YKE0004

DSBGA - 0.445mm max height

DIE SIZE BALL GRID ARRAY



SOLDER PASTE EXAMPLE
BASED ON 0.075 - 0.1mm THICK STENCIL
SCALE:40X

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NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.